

## Minutes from OpenPICs WP 4 meeting 06-02-2017

Present: Longfei, Luc, Rui, Steven, Huub, Rene

Agenda points	Responsible	Updates?
New epitaxy integration (Al-MQW, Zn diffusion)	Longfei, Rene	
Insulation and high-speed RF lines	Tjibbe, Longfei	
DUV process optimization	Roel	No updates
CMP and Stepper process development	Robert	No updates
MPW test structures design	Weiming, Longfei	No updates

### Discussion/action points

Nr.	Description	Responsible
1.	<b>Al-MQW based BBs</b> We should look into design choices (Al- or P-) in SCH and barrier layers. We can use the mask from Smart for broad area gain measurements. Weiming will check the mask layout with Rui. Longfei will prepare the process flow. The measurement should be planned carefully, so that the edge degradation (due to Al oxidation) over the time after cleaving can also be studied.	Longfei, Weiming
2.	<b>Zn diffusion tests</b> Rene will make an updated experiment plan this week according to the discussion. 3 layerstacks will be studied first: InGaAs, InP, and Smart MPW epi (provided by smart, Rene checks with Peter when this is available). Starting conditions for the test are PH3 and 100 mbar. Influence on diffusion profile will be studied w.r.t. temperature and time.	Rene, Longfei
3.	<b>BCB planarization</b> Tjibbe will ask for the quotation of BCB Cyclotene 3022-57, which should give 6 um thickness with 4000 rpm spin.	Tjibbe, Longfei

Next meeting: 13:30-15:00, 20-02-2017, Flux 10.177